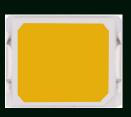


Bridgelux® SMD 2835 0.5W 3V

Product Data Sheet DS243-1





Introduction

The Bridgelux SMD 2835 mid power LED is hot-color targeted, which ensures that the LEDs fall within their specified color bin at the typical application conditions of 85°C. With its broad lumen coverage and wide range of CCT options, the SMD 2835 provides unparalleled design-in flexibility for indoor and outdoor lighting applications. The SMD 2835 is ideal as a drop-in replacement for emitters with an industry standard 2.8mm x 3.5mm footprint.

Features

- Industry-standard 2835 footprint
- 9 bin color control
- Hot-color targeting ensures that color is within the ANSI bin at the typical application conditions of 85°C
- Enables 3- and 5-step MacAdam ellipse custom binning kits
- · RoHS compliant and lead free
- Multiple CCT configurations for a wide range of lighting applications

Benefits

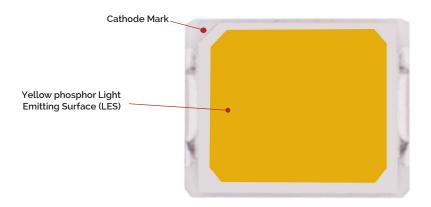
- · Lower operating and manufacturing cost
- · Ease of design and rapid go-to-market
- · Uniform, consistent white light
- · Reliable and constant white point
- · Compliant with environmental standards
- Design flexibility

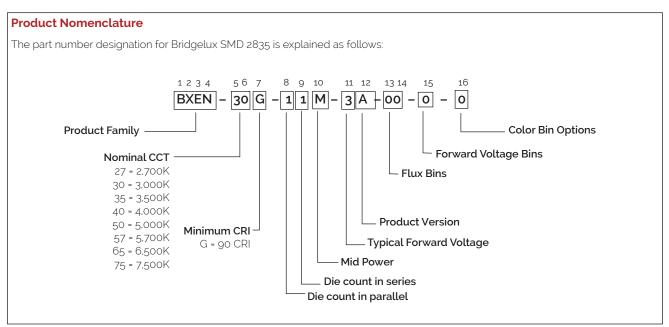
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Product Feature Map

Bridgelux SMD LED products come in industry standard package sizes and follow ANSI binning standards. These LEDs are optimized for cost and performance, helping to ensure highly competitive system lumen per dollar performance while addressing the stringent efficacy and reliability standards required for modern lighting applications.





Product Test Conditions

Bridgelux SMD 2835 LEDs are tested and binned with a 10ms pulse of 150mA at T_j (junction temperature)= T_{sp} (solder point temperature)= T_{sp} (solder point temperature)= T_{sp} of 85°C

Product Selection Guide

The following product configurations are available:

Table 1: Selection Guide, Pulsed Measurement Data at 150mA ($T_i = T_{so} = 25^{\circ}C$)

Part Number ^{1,6}	Nominal CCT ²	CRI ^{3, 5}	Nominal Drive Current	Fc	orward Voltage (V)	9 ^{4, 5}	Typical Pulsed - Flux (lm)4.5	Typical Power (W)	Typical Efficacy	
	(K)		(mA)	Min	Typical	Max	Flux (IIII)***	(w)	(lm/ W)	
BXEN-27G-11M-3A-00-0-0	2700	90	150	2.8	3.1	3.4	55	0.5	118	
BXEN-30G-11M-3A-00-0-0	3000	90	150	2.8	3.1	3.4	58	0.5	125	
BXEN-35G-11M-3A-00-0-0	3500	90	150	2.8	3.1	3.4	58	0.5	125	
BXEN-40G-11M-3A-00-0-0	4000	90	150	2.8	3.1	3.4	61	0.5	131	
BXEN-50G-11M-3A-00-0-0	5000	90	150	2.8	3.1	3.4	61	0.5	131	
BXEN-57G-11M-3A-00-0-0	5700	90	150	2.8	3.1	3.4	61	0.5	131	
BXEN-65G-11M-3A-00-0-0	6500	90	150	2.8	3.1	3.4	61	0.5	131	
BXEN-75G-11M-3A-00-0-0	7500	90	150	2.8	3.1	3.4	61	0.5	131	

Table 2: Selection Guide, Pulsed Test Performance $(T_{so} = 85^{\circ}C)^{7.8}$

Part Number ^{1,6}	Nominal CCT ²	CRI ^{3,5}	Nominal Drive Current	F	orward Voltag (V)	e ⁵	Typical Pulsed	Typical Power	Typical Efficacy	
	(K)		(mA)	Min	Typical	Max	- Flux (lm)⁵	(W)	(lm/W)	
BXEN-27G-11M-3A-00-0-0	2700	90	150	2.7	3.0	3.3	49	0.5	106	
BXEN-30G-11M-3A-00-0-0	3000	90	150	2.7	3.0	3.3	51	0.5	111	
BXEN-35G-11M-3A-00-0-0	3500	90	150	2.7	3.0	3.3	51	0.5	111	
BXEN-40G-11M-3A-00-0-0	4000	90	150	2.7	3.0	3.3	54	0.5	117	
BXEN-50G-11M-3A-00-0-0	5000	90	150	2.7	3.0	3.3	54	0.5	117	
BXEN-57G-11M-3A-00-0-0	5700	90	150	2.7	3.0	3.3	54	0.5	117	
BXEN-65G-11M-3A-00-0-0	6500	90	150	2.7	3.0	3.3	54	0.5	117	
BXEN-75G-11M-3A-00-0-0	7500	90	150	2.7	3.0	3.3	54	0.5	117	

Notes for Tables 1 & 2:

- 1. The last 6 characters (including hyphens '-') refer to flux bins, forward voltage bins, and color bin options, respectively. "00-0-0" denotes the full distribution of flux, forward voltage, and 7 SDCM color.
- Example: BXEN-30G-11M-3A-00-0-0 refers to the full distribution of flux, forward voltage, and color within a 3000K 7-step ANSI standard chromaticity region with a minimum of goCRI, 1x1 die configuration, mid power, 3.1V typical forward voltage.
- 2. Product CCT is cold targeted at Tsp = 85°C. Nominal CCT as defined by ANSI C78.377-2011.
- 3. Listed CRIs are minimum values and include test tolerance.
- 4. Products tested under pulsed condition (10ms pulse width) at nominal drive current where Tj-Tsp-25°C.
- 5. Bridgelux maintains a ±7.5% tolerance on luminous flux measurements, ±0.1V tolerance on forward voltage measurements, and ±2 tolerance on CRI measurements for the SMD 2835.
- 6. Refer to Table 6 and Table 7 for Bridgelux SMD 2835 Luminous Flux Binning and Forward Voltage Binning information.
- 7. Typical pulsed test performance values are provided as reference only and are not a guarantee of performance.
- 8. Typical performance is estimated based on operation under pulsed current with LED emitter mounted onto a heat sink with thermal interface material and the solder point temperature maintained at 25°C. Based on Bridgelux test setup, values may vary depending on the thermal design of the luminaire and/or the exposed environment to which the product is subjected.

Performance at Commonly Used Drive Currents

SMD 2835 LEDs are tested to the specifications shown using the nominal drive currents in Table 1. SMD 2835 may also be driven at other drive currents dependent on specific application design requirements. The performance at any drive current can be derived from the current vs. voltage characteristics shown in Figure 2 and the relative luminous flux vs. current characteristics shown in Figure 3. The performance at commonly used drive currents is summarized in Table 3.

Table 3: Performance at Commonly Used Drive Currents

Part Number	CRI	Drive Current¹ (mA)	Typical V _f T _{sp} = 25°C (V)	Typical Power T _{sp} = 25°C (W)	Typical Pulsed Flux ² T _{sp} = 25 °C (lm)	Typical DC Flux³ T _{sp} = 85°C (lm)	Typical Efficacy T _{sp} = 25°C (lm/W)
		30	2.8	0.1	12	11	150
		60	2.9	0.2	24	22	140
BXEN-27G-11M-3A-00-0-0	90	90	2.9	0.3	35	32	132
		120	3.0	0.4	45	41	125
		150	3.1	0.5	55	49	118
		30	2.8	0.1	13	12	158
		60	2.9	0.2	25	23	148
BXEN-30G-11M-3A-00-0-0	90	90	2.9	0.3	37	33	139
		120	3.0	0.4	48	43	132
		150	3.1	0.5	58	51	124
		30	2.8	0.1	13	12	158
		60	2.9	0.2	25	23	148
BXEN-35G-11M-3A-00-0-0	90	90	2.9	0.3	37	33	139
		120	3.0	0.4	48	43	132
		150	3.1	0.5	58	51	124
		30	2.8	0.1	14	13	166
		60	2.9	0.2	27	24	156
BXEN-40G-11M-3A-00-0-0	90	90	2.9	0.3	39	35	147
		120	3.0	0.4	50	45	138
		150	3.1	0.5	61	54	131
		30	2.8	0.1	14	13	166
		60	2.9	0.2	27	24	156
BXEN-50G-11M-3A-00-0-0	90	90	2.9	0.3	39	35	147
		120	3.0	0.4	50	45	138
		150	3.1	0.5	61	54	131
		30	2.8	0.1	14	13	166
		60	2.9	0.2	27	24	156
BXEN-57G-11M-3A-00-0-0	90	90	2.9	0.3	39	35	147
		120	3.0	0.4	50	45	138
		150	3.1	0.5	61	54	131
		30	2.8	0.1	14	13	166
		60	2.9	0.2	27	24	156
BXEN-65G-11M-3A-00-0-0	90	90	2.9	0.3	39	35	147
		120	3.0	0.4	50	45	138
		150	3.1	0.5	61	54	131
		30	2.8	0.1	14	13	166
		60	2.9	0.2	27	24	156
BXEN-75G-11M-3A-00-0-0	90	90	2.9	0.3	39	35	147
		120	3.0	0.4	50	45	138
		150	3.1	0.5	61	54	131

Notes for Tables 3:

^{1.} Alternate drive currents in Table 3 are provided for reference only and are not a guarantee of performance.

^{2.} Bridgelux maintains a ± 7.5% tolerance on flux measurements.

^{3.} Typical stabilized DC performance values are provided as reference only and are not a guarantee of performance.

Electrical Characteristics

Table 4: Electrical Characteristics

	Drive Current	Fo	orward Voltaç (V) ^{2,3}	ge	Typical Temperature Coefficient	Typical Thermal Resistance	
Part Number ¹	(mA)	Minimum Typical Max		Maximum	of Forward Voltage ∆V _r /∆T (mV/°C)	Junction to Solder Point⁴ R _{j-sp} (°C/W)	
BXEN-XXX-11M-3A-00-0-0	150	2.8	3.1	3.4	-0.87	30	

Notes for Tables 4:

- 1. The last 6 characters (including hyphens '-') refer to flux bins, forward voltage bins, and color bin options, respectively. "00-0-0" denotes the full distribution of flux, forward voltage, and 7 SDCM color.
- Example: BXEN-30G-11M-3A-00-0-0 refers to the full distribution of flux, forward voltage, and color within a 3000K 7-step ANSI standard chromaticity region with a minimum of 90CRI, 1x1 die configuration, mid power, 31V typical forward voltage.
- 2. Bridgelux maintains a tolerance of ± 0.1V on forward voltage measurements. Voltage minimum and maximum values at the nominal drive current are guaranteed by 100% test.
- 3. Products tested under pulsed condition (10ms pulse width) at nominal drive current where Tsp = 25°C.
- 4. Thermal resistance value was calculated using total electrical input power; optical power was not subtracted from input power.

Absolute Maximum Ratings

Table 5: Maximum Ratings

Parameter	Maximum Rating				
LED Junction Temperature (T _j)	125°C				
Storage Temperature	-40°C to +105°C				
Operating Solder Point Temperature (T _{Sp})	-40°C to +105°C				
Soldering Temperature	260°C or lower for a maximum of 10 seconds				
Maximum Drive Current	150mA				
Maximum Peak Pulsed Forward Current ¹	300mA				
Maximum Reverse Voltage²	-				
Moisture Sensitivity Rating	MSL 3				
Electrostatic Discharge	2kV HBM. JEDEC-JS-001-HBM and JEDEC-JS-001-2012				

Notes for Tables 5:

^{1.} Bridgelux recommends a maximum duty cycle of 10% and pulse width of 10 ms when operating LED SMD at maximum peak pulsed current specified. Maximum peak pulsed current indicate values where LED SMD can be driven without catastrophic failures.

^{2.} Light emitting diodes are not designed to be driven in reverse voltage and will not produce light under this condition. no rating is provided.

Product Bin Definitions

Table 6 lists the standard photometric luminous flux bins for Bridgelux SMD 2835 LEDs. Although several bins are listed, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all CCTs.

Table 6: Luminous Flux Bin Definitions at 150mA, T_{sp} =25°C

Bin Code	Minimum	Maximum	Unit	Condition
2A	50	55		
2B	55	60	lm	-150mΛ
2C	60	65	ł lm	I _F =150mA
2D	65	70		

Note for Tables 6:

Table 7: Forward Voltage Bin Definition at 150mA, $T_{\rm sp}$ =25 $^{\circ}$ C

Bin Code	Minimum	Maximum	Unit	Condition
А	2.8	2.9		
В	2.9	3.0		
С	3.0	3.1	.,	1 . A
D	3.1	3.2	V	I _F =150mA
Е	3.2	3.3		
F	3.3	3.4		

Note for Tables 7:

^{1.} Bridgelux maintains a tolerance of \pm 7.5% on luminous flux measurements.

^{1.} Bridgelux maintains a tolerance of ± 0.1V on forward voltage measurements.

Product Bin Definitions

Table 8: 3- and 5-step MacAdam Ellipse Color Bin Definitions

C	СТ	Colo	w 6 m a a a		Се	nter Poi	nt		Moies A	via	Minor	Avia	El	lipse		Color B	i.e
J.	٠.	Colo	r Space		Х		Υ		Major A	IXIS	Minor	AXIS	Rotati	on Angl	е	Color B	ırı
070	201/	35	SDCM	(0.4578		0.4101		0.00810		0.00420		53.70			1	
2/0	ooK	5.5	SDCM	(0.4578		0.4101		0.0135	50	0.00700		53.70		1	1/A/B/C/D	
	.,	3 5	SDCM	(0.4338		0.4030		0.008;	34	0.00	408	5	3.22		1	
300	ooK	5.5	SDCM	(0.4338		0.4030		0.0139	90	0.00	680	5	3.22	1	./A/B/C	C/D
		3 5	SDCM	(0.4073		0.3917		0.009	27	0.00	414	5	4.00		1	
350	ooK	5.5	SDCM	(0.4073		0.3917		0.0154	45	0.00	690	5	4.00	1	./A/B/C	C/D
	14	35	SDCM	(0.3818		0.3797		0.009;	39	0.00	402	5	3.72		1	
400	ooK	5.5	SDCM	(0.3818		0.3797		0.0156	55	0.00	670	5	3.72	1	./A/B/C	C/D
	1.6	35	SDCM	(0.3447		0.3553		0.008	22	0.00	354	5	9.62		1	
500	ooK	5.5	SDCM	(0.3447		0.3553		0.0137	70	0.00	590	5	9.62	1	/A/B/C	C/D
		35	SDCM	(0.3287		0.3417		0.0074	46	0.00	320	5	9.09		1	
570	ooK	5.5	SDCM	(0.3287		0.3417		0.0124	13	0.00	0.00533		59.09		1/A/B/C/D	
		35	SDCM		0.3123		0.3282		0.00669		0.00285		58.57			1	
650	6500K		SDCM		0.3123		0.3282		0.01115		0.00475		58.57		1	1/A/B/C/D	
750	ооК	35	SDCM	(0.3000		0.3250		0.006	69	0.00285		58.57			1	
	25°C	5.5	SDCM	(0.3000		0.3250		0.0111	15	0.00	475	5	8.57	1	./A/B/C	C/D
		nol/		оооК		a a l		201/		201/		201/	6-4	201/	75	ооК	
Point	2/0	ooK 	300	JUK	350	ooK 	400	ooK	500	ooK 	5700K		6500K		T _{sp} =	25°C	Color Bin
	х	у	x	у	x	у	х	У	х	У	х	у	х	у	x	У	
	0.4813	0.4319	0.4562	0.4260	0.4299	0.4165	0.4006	0.4044	0.3551	0.3760	0.3376	0.3616	0.3205	0.3481	0.3074	0.3441	
ANSI	0.4562	0.426	0.4299	0.4165	0.3996	0.4015	0.3736	0.3874	0.3376	0.3616	0.3207	0.3462	0.3028	0.3304	0.2897	0.3264	
711131	0.4373	0.3893	0.4147	0.3814	0.3889	0.3690	0.3670	0.3578	0.3366	0.3369	0.3222	0.3243	0.3068	0.3113	0.2937	0.3073	
	0.4593	0.3944	0.4373	0.3893	0.4147	0.3814	0.3898	0.3716	0.3515	0.3487	0.3366	0.3369	0.3221	0.3261	0.3090	0.3221	E/F/
V-up	0.4687	0.4289	0.4431	0.4213	0.4148	0.4090	0.3871	0.3959	0.3463	0.3687	0.3290	0.3538	0.3115	0.3391	0.2986	0.3353	G/H
	0.4618	0.4170	0.4377	0.4101	0.4112	0.3996	0.3847	0.3873	0.3457	0.3617	0.3290	0.3470	0.3124	0.3328	0.2994	0.3289	
V-down	0.4483	0.3919	0.4260	0.3854	0.4018	0.3752	0.3784	0.3647	0.3440	0.3427	0.3290	0.3300	0.3144	0.3186	0.3014	0.3147	
	0.4542	0.4031	0.4310	0.3960	0.4053	0.3844	0.3807	0.3730	0.3445	0.3495	0.3290	0.3369	0.3135	0.3250	0.3005	0.3210	
H-left	0.4468	0.4077	0.4223	0.3990	0.3941	0.3848	0.3702	0.3722	0.3371	0.3490	0.3215	0.3350	0.3048	0.3207	0.2917	0.3169	
	0.4524	0.4089	0.4283	0.4013	0.4012	0.3885	0.3755	0.3755	0.3395	0.3509	0.3240	0.3372	0.3081	0.3240	0.2958	0.3208	
H-right	0.4703	0.4132	0.4468	0.4077	0.4223	0.3990	0.3950	0.3875	0.3533	0.3620	0.3371	0.3490	0.3213	0.3373	0.3082	0.3331	
	0.4632	0.4115	0.4394	0.4052	0.4133	0.3945	0.3880	0.3834	0.3498	0.3592	0.3334	0.3456	0.3165	0.3325	0.3042	0.3292	
Center	0.4578	0.4101	0.4338	0.4030	0.4073	0.3917	0.3818	0.3797	0.3447	0.3553	0.3287	0.3417	0.3123	0.3282	0.3000	0.3250	

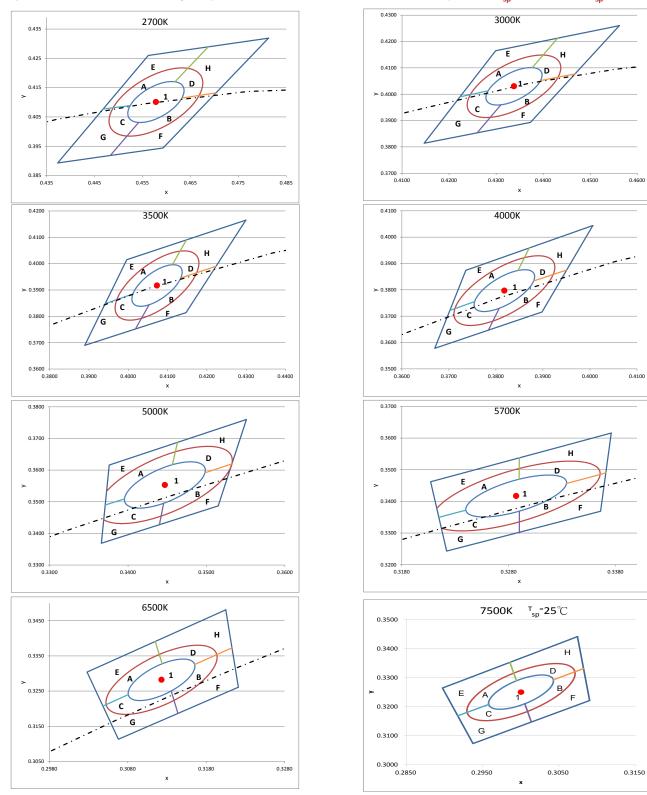
Notes for Tables 8:

^{1.} Color binning at $T_{\rm sp}$ =85 $^{\circ}$ C unless otherwise specified

^{2.} Bridgelux maintains a tolerance of \pm 0.007 on x and y color coordinates in the CIE 1931 color space.

Product Bin Definitions

Figure 1: C.I.E. 1931 Chromaticity Diagram (9 Color Bin Structure, Hot-color Targeted at T_{sp} =85°C, 75G at T_{sp} =25°C)



0.4600

Performance Curves

Figure 2: Drive Current vs. Voltage (T_{sp}=25°C)

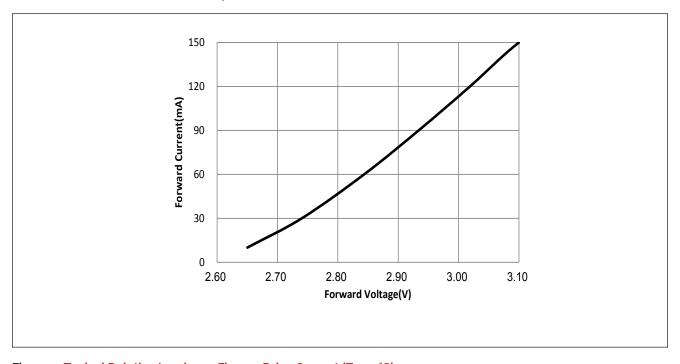
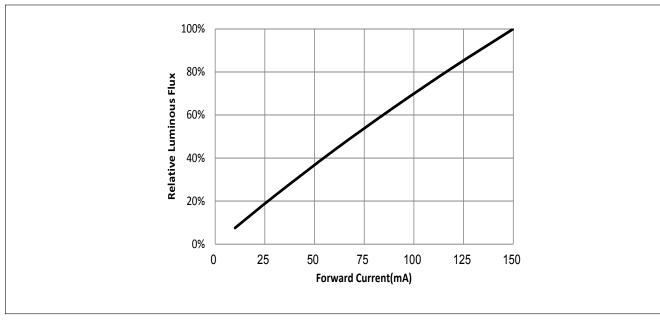


Figure 3: Typical Relative Luminous Flux vs. Drive Current (T_{sp}=25°C)



Note for Figure 3:

^{1.} Bridgelux does not recommend driving mid power LEDs at low currents. Doing so may produce unpredictable results. Pulse width modulation (PWM) is recommended for dimming effects.

Performance Curves

Figure 4: Typical Relative Flux vs. Solder Point Temperature

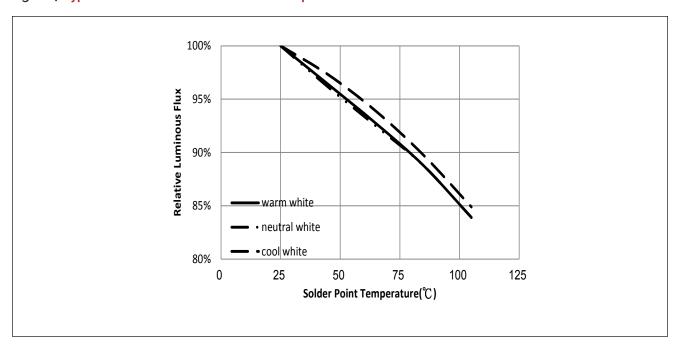
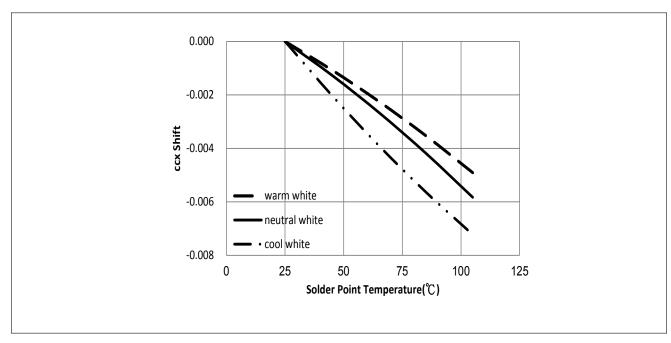


Figure 5: Typical ccx Shift vs. Solder Point Temperature



Notes for Figures 4 & 5:

- 1. Characteristics shown for warm white based on 3000K and 90 CRI.
- 2. Characteristics shown for neutral white based on 4000K and 90 CRI.
- 3. Characteristics shown for cool white based on 5000K and 90 CRI.
- 4. For other color SKUs, the shift in color will vary. Please contact your Bridgelux Sales Representative for more information.

Performance Curves

0.000 -0.002 -0.004 **Solution Spit** -0.006 **CC Spit** -0.008 - warm white -0.010 neutral white -0.012 cool white -0.014 0 25 50 75 100 125 Solder Point Temperature(℃)

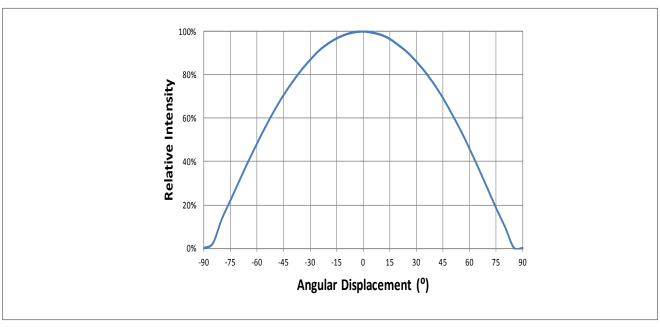
Figure 6: Typical ccy Shift vs. Solder Point Temperature

Notes for Figure 6:

- 1. Characteristics shown for warm white based on 3000K and 90 CRI.
- 2. Characteristics shown for neutral white based on 4000K and 90 CRI.
- 3. Characteristics shown for cool white based on 5000K and 90 CRI.
- 4. For other color SKUs, the shift in color will vary. Please contact your Bridgelux Sales Representative for more information.

Typical Radiation Pattern

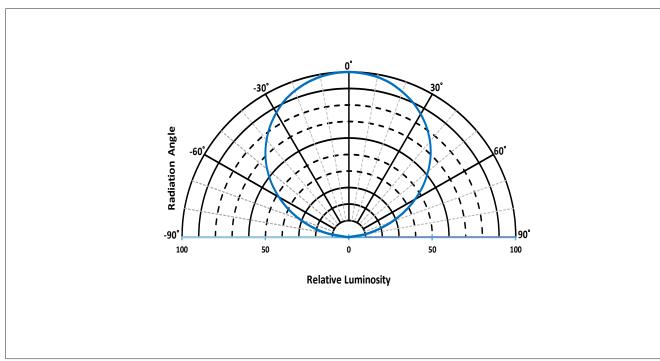
Figure 7: Typical Spatial Radiation Pattern at 150mA, T_{sp} =25°C



Notes for Figure 7:

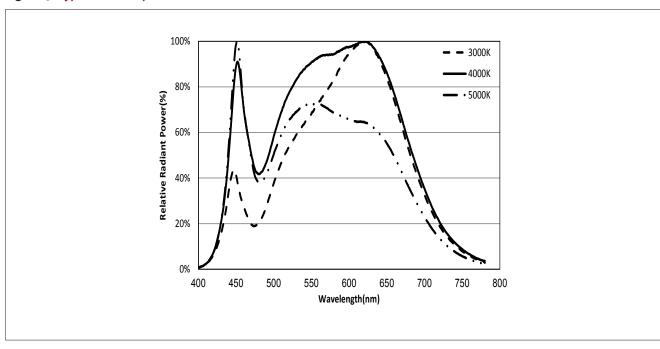
- 1. Typical viewing angle is 120°.
- 2. The viewing angle is defined as the off axis angle from the centerline where luminous intensity (Iv) is ½ of the peak value.

Figure 8: Typical Polar Radiation Pattern at 150mA, T_{sp} =25°C



Typical Color Spectrum

Figure 9: Typical Color Spectrum

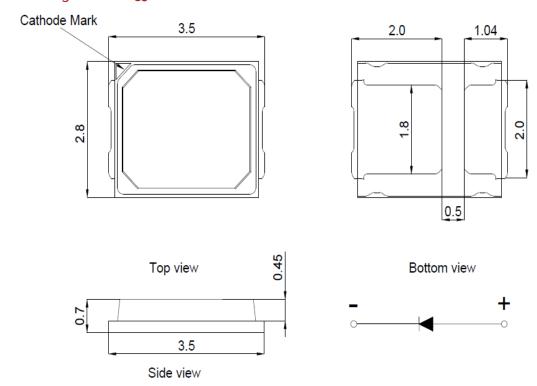


Notes for Figure 9:

- 1. Color spectra measured at nominal current for Tsp = 25°C
- 2. Color spectra shown for 90 CRI products.

Mechanical Dimensions

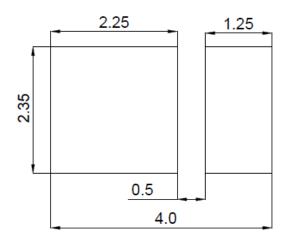
Figure 10: Drawing for SMD 2835



Notes for Figure 10:

- 1. Drawings are not to scale.
- 2. Drawing dimensions are in millimeters.
- 3. Unless otherwise specified, tolerances are ± 0.10mm.

Recommended PCB Soldering Pad Pattern



Reliability

Table 9: Reliability Test Items and Conditions

No.	ltems	Reference Standard	Test Conditions	Drive Current	Test Duration	Units Failed/Tested
1	Moisture/Reflow Sensitivity	J-STD-020E	T _{sld} = 260°C, 10sec, Precondition: 60°C, 60%RH, 168hr	-	3 reflows	0/22
2	Low Temperature Storage	JESD22-A119	T _a =-40°C	-	1000 hours	0/22
3	High Temperature Storage	JESD22-A103D	T _a = 100°C	-	1000 hours	0/22
4	Low Temperature Operating Life	JESD22-A108D	T _a =-40°C	150mA	1000 hours	0/22
5	Temperature Humidity Operating Life	JESD22-A101C	T _{sp} =85°C, RH=85%	150mA	1000 hours	0/22
6	High Temperature Operating Life	JESD22-A108D	T _{sp} =85°C	150mA	1000 hours	0/22
7	Power switching	IEC62717:2014	T _{sp} = 85°C 30 sec on, 30 sec off	150mA	30000 cycles	0/22
8	Thermal Shock	JESD22-A106B	T _a =-40°C ~100°C; Dwell : 15min; Transfer: 10sec	-	200 cycles	0/22
9	Temperature Cycle	JESD22-A104E	T _a =-40°C ~100°C; Dwell at extreme temperature: 15min; Ramp rate < 105°C/min	-	200 cycles	0/22
10	Electrostatic Discharge	JS-001-2012	HBM, 2KV, 1.5kΩ, 100pF, Alternately positive or negative	-	-	0/22

Passing Criteria

Item	Symbol	Symbol Test Condition			
Forward Voltage	Vf	150mA	ΔVf<10%		
Luminous Flux	Fv	150mA	∆Fv<30%		
Chromaticity Coordinates	(x, y)	150mA	Δu'v'<0.007		

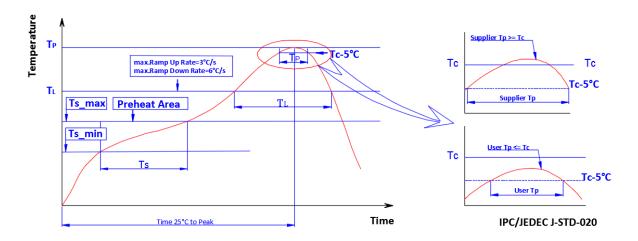
Notes for Tables 9:

^{1.} Measurements are performed after allowing the LEDs to return to room temperature

^{2.} $T_{\rm sld}$: reflow soldering temperature; $T_{\rm a}$: ambient temperature

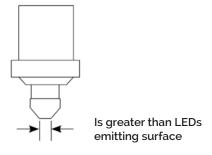
Reflow Characteristics

Figure 11: Reflow Profile



Profile Feature	Lead Free Assembly		
Temperature Min. (Ts_min)	160°C		
Temperature Max. (Ts_max)	205°C		
Time (ts) from Ts_min to Ts_max	60-150 seconds		
Ramp-Up Rate (TL to Tp)	3 °C/second		
Liquidus Temperature (TL)	220 °C		
Time (TL) Maintained Above TL	60-150 seconds		
Peak Temp(Tp)	260 °C max.		
Time (Tp) Within 5 °C of the Specified Classification Temperature (Tc)	25 seconds max.		
Ramp-Down Rate (Tp to TL)	5 °C/second max.		
Time 25 °C to Peak Temperature	10 minutes max.		

Figure 12: Pick and Place

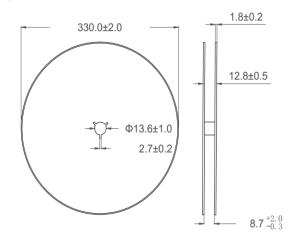


Note for Figure 12:

^{1.} When using a pick and place machine, choose a nozzle that has a larger diameter than the LED's emitting surface. Using a Pick-and-Place nozzle with a smaller diameter than the size of the LEDs emitting surface will cause damage and may also cause the LED to not illuminate.

Packaging

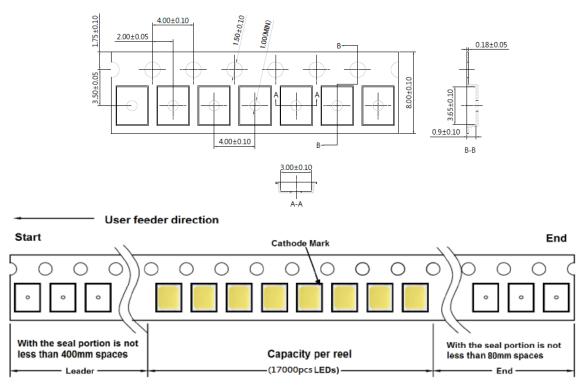
Figure 13: Emitter Reel Drawings



Note for Figure 13:

1. Drawings are not to scale. Drawing dimensions are in millimeters.

Figure 14: Emitter Tape Drawings

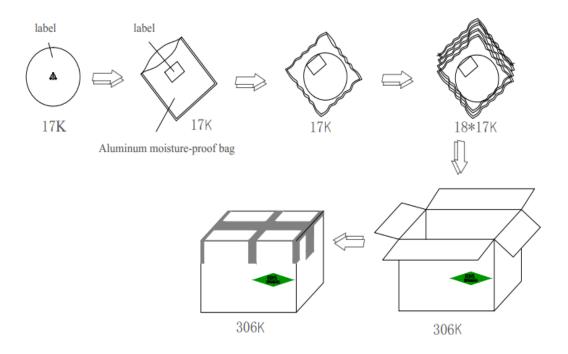


Note for Figure 14:

1. Drawings are not to scale. Drawing dimensions are in millimeters.

Packaging

Figure 15: Emitter Reel Packaging Drawings



Note for Figure 15:

1. Drawings are not to scale.

Design Resources

Please contact your Bridgelux sales representative for assistance.

Precautions

CAUTION: CHEMICAL EXPOSURE HAZARD

Exposure to some chemicals commonly used in luminaire manufacturing and assembly can cause damage to the LED emitter. Please consult Bridgelux Application Note AN51 for additional information.

CAUTION: EYE SAFETY

Eye safety classification for the use of Bridgelux SMD LED emitter is in accordance with IEC specification EN62471: Photobiological Safety of Lamps and Lamp Systems. SMD LED emitters are classified as Risk Group 1 when operated at or below the maximum drive current. Please use appropriate precautions. It is important that employees working with LEDs are trained to use them safely.

CAUTION: RISK OF BURN

Do not touch the SMD LED emitter during operation. Allow the emitter to cool for a sufficient period of time before handling. The SMD LED emitter may reach elevated temperatures such that could burn skin when touched.

CAUTION

CONTACT WITH LIGHT EMITTING SURFACE (LES)

Avoid any contact with the LES. Do not touch the LES of the emitter or apply stress to the LES (yellow phosphor resin area). Contact may cause damage to the emitter

Optics and reflectors must not be mounted in contact with the LES (yellow phosphor resin area).

Disclaimers

MINOR PRODUCT CHANGE POLICY

The rigorous qualification testing on products offered by Bridgelux provides performance assurance. Slight cosmetic changes that do not affect form, fit, or function may occur as Bridgelux continues product optimization.

STANDARD TEST CONDITIONS

Unless otherwise stated, LED emitter testing is performed at the nominal drive current.

About Bridgelux: Bridging Light and Life™

At Bridgelux, we help companies, industries and people experience the power and possibility of light. Since 2002, we've designed LED solutions that are high performing, energy efficient, cost effective and easy to integrate. Our focus is on light's impact on human behavior, delivering products that create better environments, experiences and returns—both experiential and financial. And our patented technology drives new platforms for commercial and industrial luminaires.

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